

## UMF Equipment – Dicing Saw

### Dicing Saw DAD3220

#### Introduction:

DISCO DAD3220 is a compact high performance single spindle automatic dicing saw for dice cut or groove semiconductor wafers with electronic component materials such as glasses and ceramics etc. The system is equipped with LCD touch panel with a graphical user interface for easy and intuitive operation. The high power 1.5 kW spindle features a shaft lock function for easier blade changing.

#### Features / Specifications:

- Spindle output: 1.5 kW
- Torque: 0.48 Nm
- Z-axis moving resolution: 0.05  $\mu\text{m}$
- $\theta$  maximum rotating angle: 320°
- 6" tape cut chuck table
- Macro microscope allows for a greater field of view
- Auto-alignment, auto-focus, and auto-kerf check functions for enhanced productivity
- Blade breakage detection

Please refer to supplier information page for further details of the system:

<https://www.disco.co.jp/eg/products/dicer/dad3220.html>

For inquiry, please contact Dr. Hardy Lui (Tel: 2766 7791; Email: [hardy.lui@polyu.edu.hk](mailto:hardy.lui@polyu.edu.hk)).

